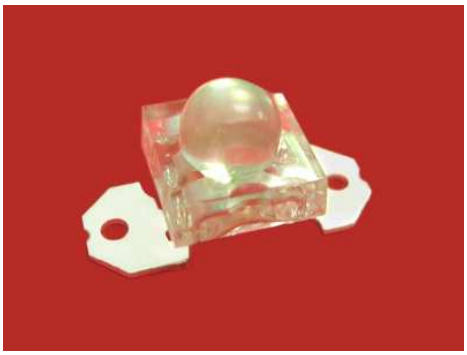
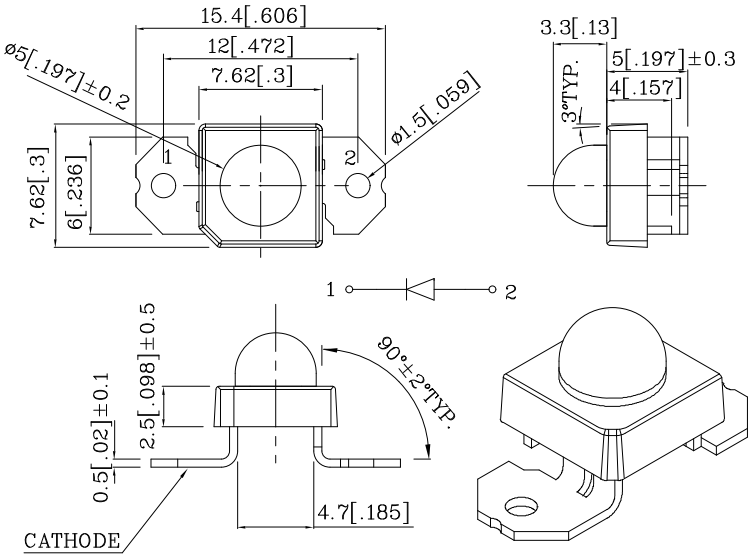
SunLED
www.SunLEDusa.com

Part Number: **XSDG93W**

SnapLED

PRELIMINARY SPEC





Features:

- HIGH LUMINANCE OUTPUT.
- DESIGN FOR HIGH CURRENT OPERATION.
- SOLDERLESS MOUNTING TECHNIQUE.
- LOW POWER CONSUMPTION.
- LOW THERMAL RESISTANCE.
- LOW PROFILE.
- PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT.
- RoHS COMPLIANT.

ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Benefits

*Rugged Lighting Products.
*Electricity savings.
*Maintenance savings.
*Environmental Conformance.

Typical Applications

*Automotive Exterior Lighting.
*Solid State Lighting and Signaling.

Absolute Maximum Ratings (T_A=25°C)		**DG (AlInGaN)**	**Unit**
Reverse Voltage	V_R	5	V
DC Forward Current	I_F	30	mA
Power Dissipation	P_T	126	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	Tstg	-55 ~ +85	
Electrostatic Discharge Threshold (HBM)		450	V

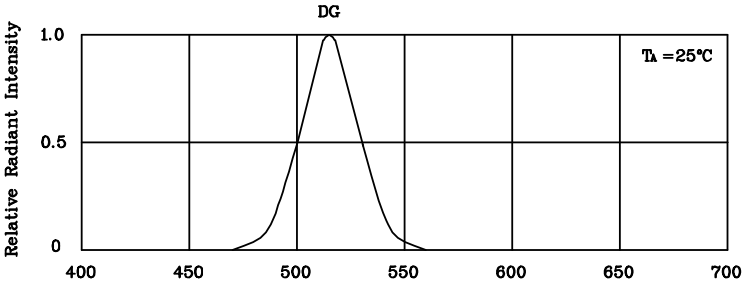
Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Operating Characteristics (T_A=25°C)		**DG (AlInGaN)**	**Unit**
Forward Voltage (Typ.) (I_F=30mA)	V_F	3.4	V
Forward Voltage (Max.) (I_F=30mA)	V_F	4.2	V
Reverse Current (Max.) (V_R=5V)	I_R	10	uA
Wavelength Of Peak Emission (Typ.) (I_F=30mA)	λ P	515	nm
Wavelength Of Dominant Emission (Typ.) (I_F=30mA) [1]	λ D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=30mA)	Δλ	30	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	45	pF
Thermal Resistance (Typ.)	Rθj -pin	150	°C/W

1.The dominant wavelength is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.

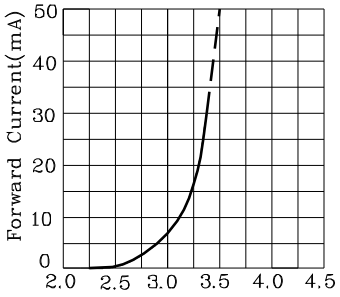
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=30mA) mcd		Luminous Flux (IF=30mA) mlm	Wavelength nm λ P	Viewing Angle 2 θ 1/2
				Min.	Typ.	Typ.		
XSDG93W	Green	AlInGaN	Water Clear	4700	7490	4200	515	30°

1.LUMINOUS INTENSITY IS MEASURED WITH AN INTEGRATING SPHERE AFTER THE DEVICE HAS STABILIZED.
2. θ 1/2 IS THE ANGLE FROM OPTICAL CENTERLINE WHERE THE LUMINOUS INTENSITY IS 1/2 THE OPTICAL CENTERLINE VALUE.

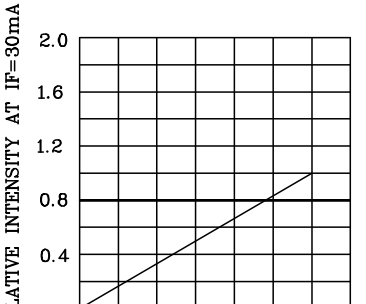


RELATIVE INTENSITY Vs. WAVELENGTH

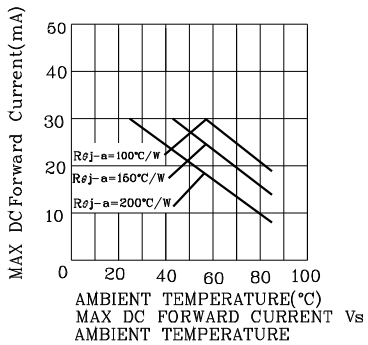
❖ DG



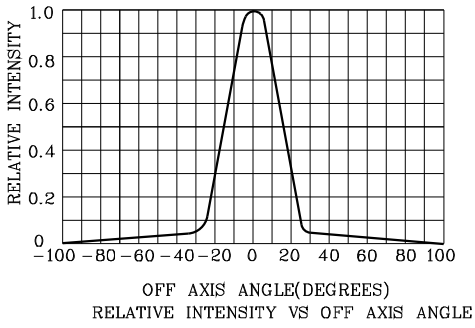
FORWARD CURRENT Vs.
FORWARD VOLTAGE



RELATIVE INTENSITY Vs.
FORWARD CURRENT

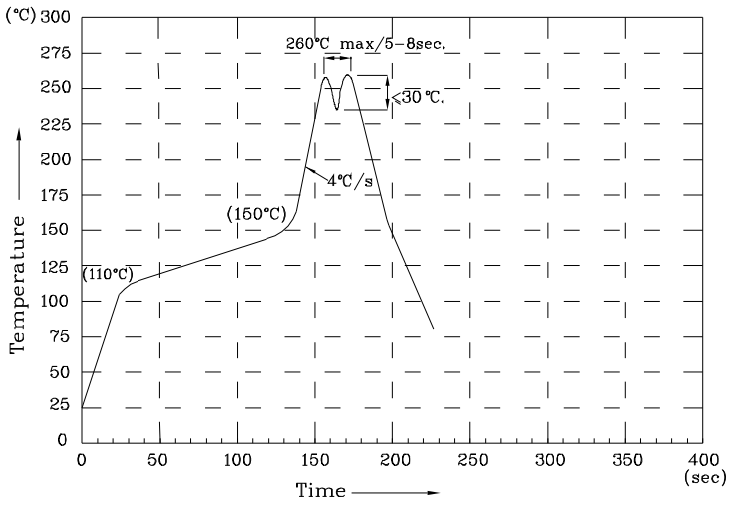


MAX DC FORWARD CURRENT Vs
AMBIENT TEMPERATURE



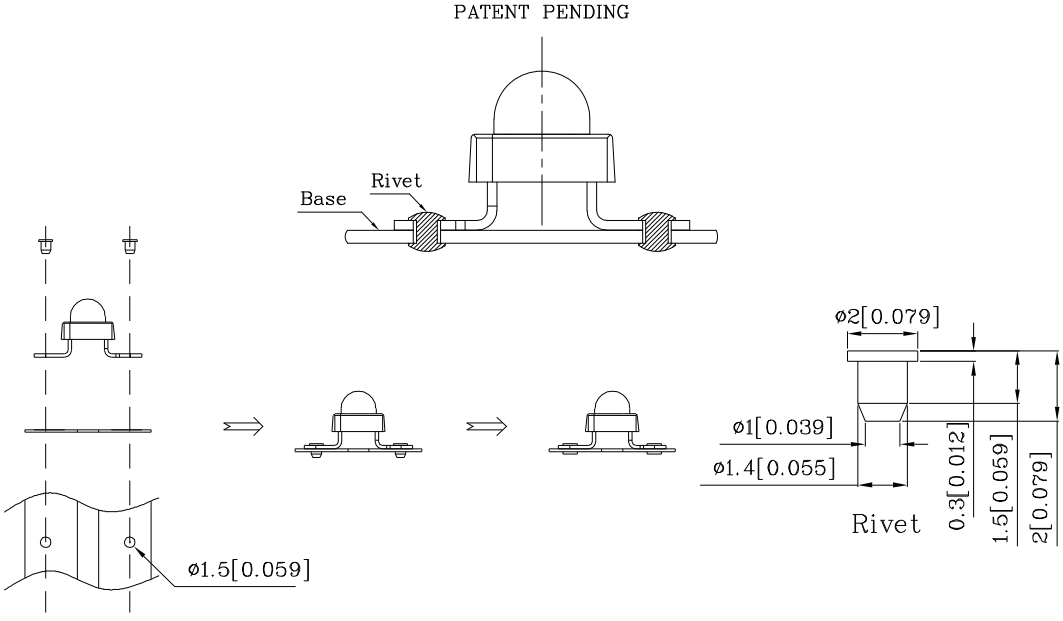
RELATIVE INTENSITY VS OFF AXIS ANGLE

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245℃~260℃. The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85 degree℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.



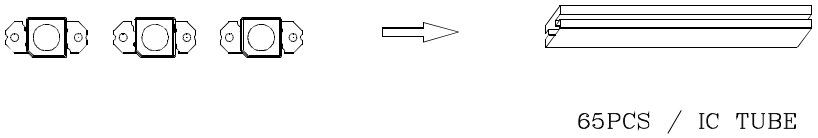
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

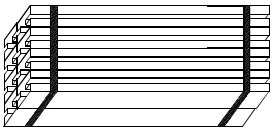
1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

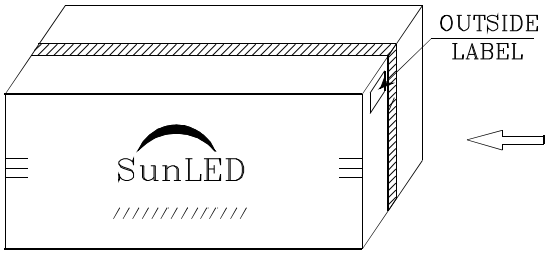
PACKING & LABEL SPECIFICATIONS XSDG93W



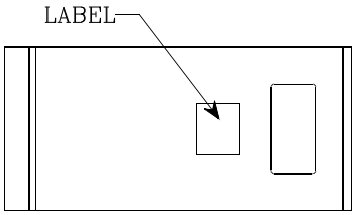
65PCS / IC TUBE



520pcs / 8pcs IC TUBE



5.2K/ BOX



8pcs IC TUBE / BAG